

REMARKS

The Communication of December 28, 2004, has been received and reviewed.

Claims 1-45 are currently pending and under consideration in the above-referenced application. Claims 46-52 have been withdrawn from consideration as being drawn to a non-elected invention. Each of claims 1-45 has been objected to.

Reconsideration and substantive examination of the above-referenced application are respectfully requested in view of the remarks herein.

Supplemental Information Disclosure Statement

Please note that Information Disclosure Statements were filed in the above-referenced application on December 15, 2003, March 8, 2004, and October 1, 2004, but the undersigned attorney has not yet received any indication that the references cited in the Information Disclosure Statements have been considered in the above-referenced application. It is respectfully requested that the references cited in the three Information Disclosure Statements be considered and made of record in the above-referenced application and that an initialed copy of the Form PTO/SB/08A that accompanied each Information Disclosure Statement be returned to the undersigned attorney as evidence of such consideration.

Objection to Title

The title of the invention was objected to as being "not descriptive." Applicants respectfully submit that the title is descriptive since the elements of the title are found in the claims. For instance, claim 1 is directed to a semiconductor device package comprising a semiconductor device including at least one bond pad on an active surface thereof; at least one outer connector positioned on a peripheral edge of the semiconductor device and having a height that extends substantially along a height of the peripheral edge; claim 13 is directed to an intermediate semiconductor device structure comprising at least two semiconductor devices; and claim 23 is directed to a semiconductor device assembly comprising a support substrate, at least one conductive column and at least one semiconductor device including an outer connector on a peripheral edge thereof.

Thus, applicants respectfully submit that the present title SEMICONDUCTOR DEVICES INCLUDING PERIPHERALLY LOCATED BOND PADS, INTERMEDIATES THEREOF, ASSEMBLIES, AND PACKAGES INCLUDING THE SEMICONDUCTOR DEVICES, AND SUPPORT ELEMENTS FOR THE SEMICONDUCTOR DEVICES is descriptive of the claims. Withdrawal of the objection is requested.

Objections to Specification

The disclosure was objected to under 37 CFR 1.71, as assertedly “being so incomprehensible as to preclude a reasonable search of the prior art by the examiner... The disclosure is objected to because of the following informalities: It appears that some of the reference numbers are not the same as described in the specification.” (Office Action at page 2). Applicants’ representatives have reviewed the as-filed specification and drawings and do not see any such discrepancies. For instance, the reference numbers (*i.e.*, 13, 15, 15’, 15’’, 17) identified in the Office Action as not being in the drawings are also not present in the specification. Further, all the reference numbers in the drawings are found in the specification.

Thus, further clarification or withdrawal of the objections to the disclosure is requested.

Drawings

The drawings have been objected to because some of the reference numerals shown in the drawings were asserted to be not the same as those shown in the specification. Specifically, it was noted that “the drawings are objected to because all the specification reference numbers are not shown in the drawings. For example, reference numbers 8, 13, 15, 15’, 15’’, 17 etc.” (*Id.* at page 3).

The applicants’ representatives have reviewed the as-filed specification and drawings and note that reference number 8 is shown in FIGS. 1 and 2. Further, reference number 8 is indicated in the specification to be “a substrate blank 8,” as shown in FIGS. 1 and 2. (*See, Specification* as-filed, paragraph [0038]). Thus, reference number 8 is shown in the drawings.

With regard to reference numbers 13, 15, 15’, 15’’, 17, applicants’ representatives have reviewed the as-filed specification and drawings and do not see any such reference numbers. Thus, further clarification or withdrawal of the objections to the drawings is requested.

ELECTION OF SPECIES REQUIREMENT

It is respectfully submitted that claims 1-5, 8-10, 12-15, 19-31, 34-39 and 42-45 remain generic to all of the species of invention that were identified in the Election of Species Requirement in the above-referenced application. In view of the allowability of these claims, claims 46-52, which have been withdrawn from consideration, should also be considered and allowed. M.P.E.P. § 806.04(d).

CONCLUSION

It is respectfully submitted that each of claims 1-52 is allowable. An early notice of the allowability of each of these claims is respectfully solicited, as is an indication that the above-referenced application has been passed for issuance. If any issues preventing allowance of the above-referenced application remain which might be resolved by way of a telephone conference, the Office is kindly invited to contact the undersigned attorney.

Respectfully submitted,



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